



PMV52ENEA

30 V, N-channel Trench MOSFET

7 May 2019

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Extended temperature range $T_j = 175 \text{ }^\circ\text{C}$
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 1 kV HBM (class H1C)
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

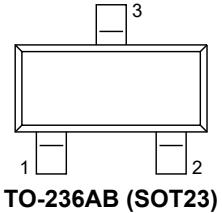
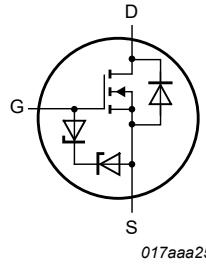
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25 \text{ }^\circ\text{C}$		-	-	30	V
V_{GS}	gate-source voltage			-20	-	20	V
I_D	drain current	$V_{GS} = 10 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$	[1]	-	-	3.2	A
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 3.2 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	52	70	$\text{m}\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm^2 .

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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 TO-236AB (SOT23)	 017aaa255
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMV52ENEA	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

7. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMV52ENEA	HQ%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

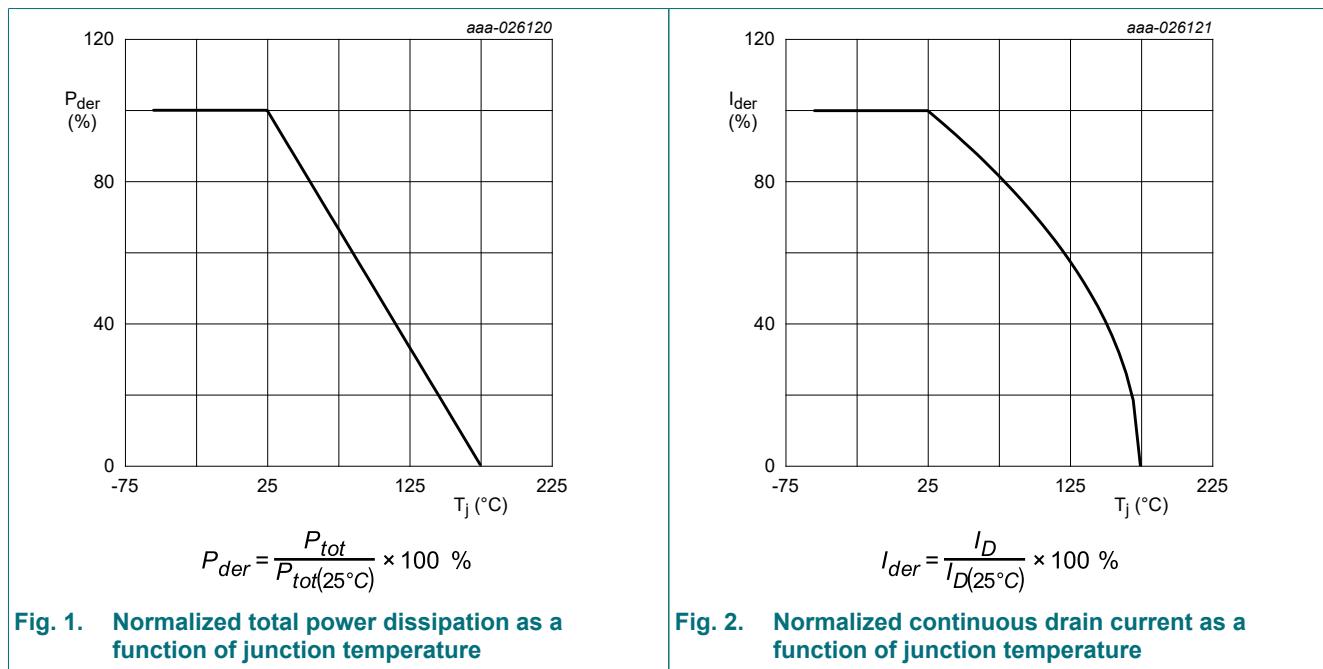
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	30	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C	[1]	-	3.2	A
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 µs		-	13	A
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	630	mW
			[1]	-	1.25	W
		T _{sp} = 25 °C		-	5.7	W
T _j	junction temperature			-55	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	1.3	A
ESD maximum rating						
V _{ESD}	electrostatic discharge voltage	HBM	[3]	-	1000	V
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{j(init)} = 25 °C; I _D = 0.25 A; DUT in avalanche (unclamped)		-	3.8	mJ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



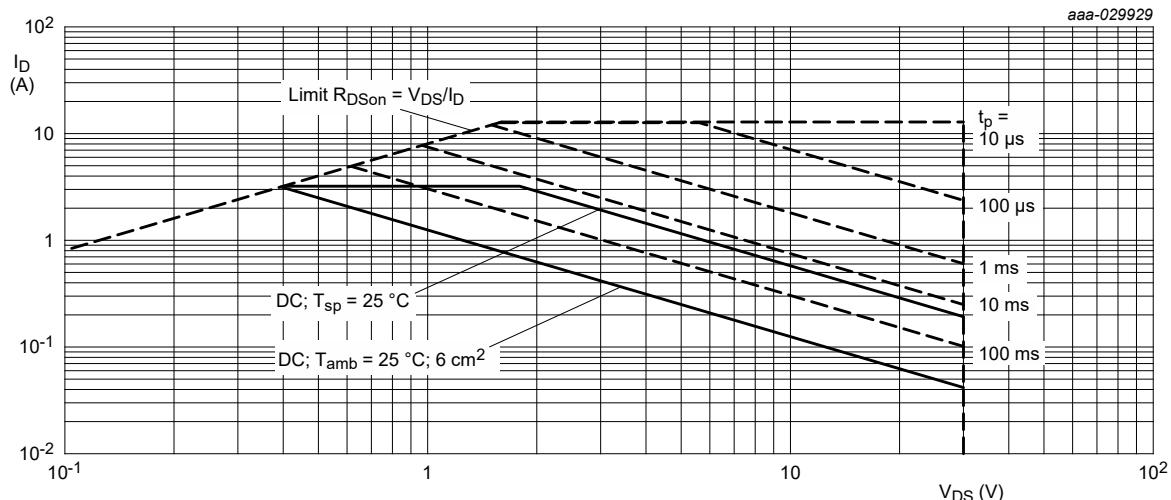


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

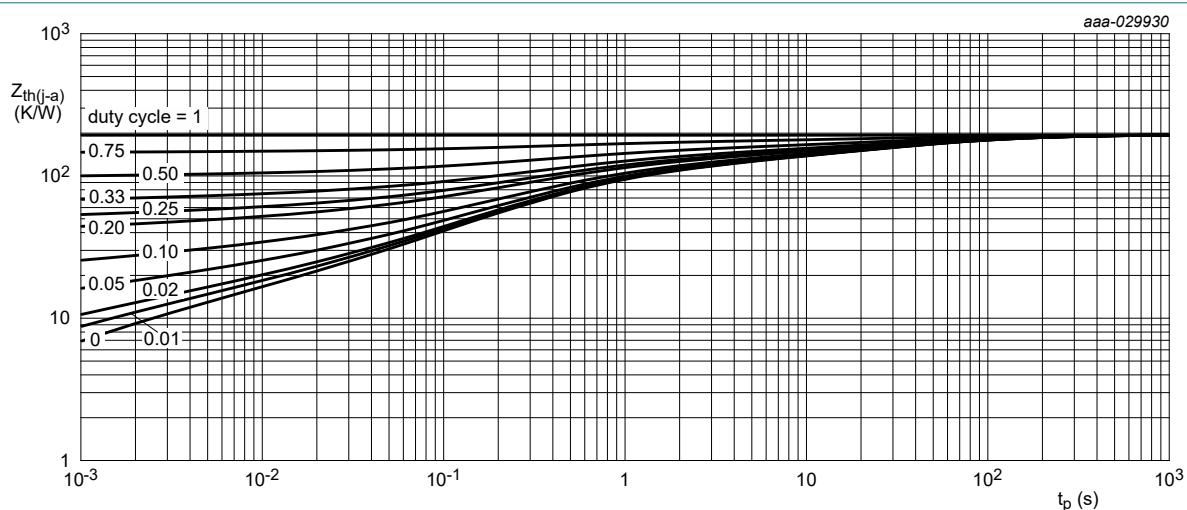
9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	195	235	K/W
			[2]	-	100	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	18	26	K/W

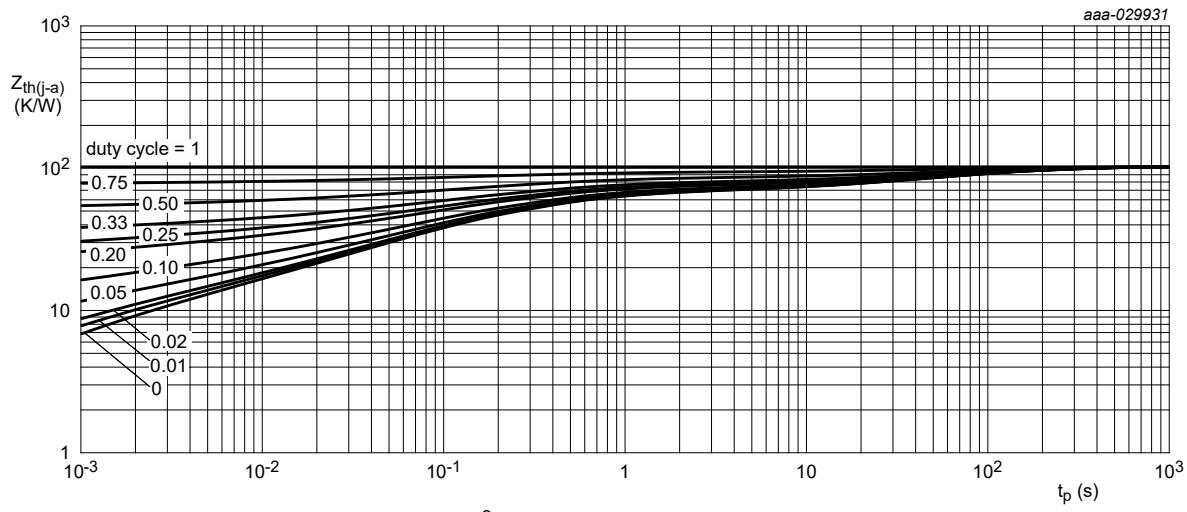
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for drain 6 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25^\circ C$		30	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu A; V_{DS} = V_{GS}; T_j = 25^\circ C$		1	1.5	2.5	V
I_{DSS}	drain leakage current	$V_{DS} = 30 V; V_{GS} = 0 V; T_j = 25^\circ C$		-	-	1	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	10	μA
		$V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	-10	μA
		$V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	2	μA
		$V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	-2	μA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 3.2 A; T_j = 25^\circ C$		-	52	70	$m\Omega$
		$V_{GS} = 10 V; I_D = 3.2 A; T_j = 175^\circ C$		-	93	124	$m\Omega$
		$V_{GS} = 4.5 V; I_D = 2.7 A; T_j = 25^\circ C$		-	70	100	$m\Omega$
g_{fs}	forward transconductance	$V_{DS} = 10 V; I_D = 3.2 A; T_j = 25^\circ C$		-	5	-	S
R_G	gate resistance	$f = 1 \text{ MHz}$		-	2	-	Ω
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$V_{DS} = 15 V; I_D = 3.2 A; V_{GS} = 10 V; T_j = 25^\circ C$		-	2.2	3.3	nC
Q_{GS}	gate-source charge			-	0.3	-	nC
Q_{GD}	gate-drain charge			-	0.6	-	nC
C_{iss}	input capacitance	$V_{DS} = 15 V; f = 1 \text{ MHz}; V_{GS} = 0 V; T_j = 25^\circ C$		-	100	-	pF
C_{oss}	output capacitance			-	30	-	pF
C_{rss}	reverse transfer capacitance			-	19	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15 V; I_D = 3.2 A; V_{GS} = 10 V; R_{G(ext)} = 6 \Omega; T_j = 25^\circ C$		-	2	-	ns
t_r	rise time			-	13	-	ns
$t_{d(off)}$	turn-off delay time			-	6	-	ns
t_f	fall time			-	3	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	$I_S = 1.3 A; V_{GS} = 0 V; T_j = 25^\circ C$		-	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 1 A; dI_S/dt = -100 A/\mu s; V_{GS} = 0 V; V_{DS} = 15 V; T_j = 25^\circ C$		-	6	-	ns
Q_r	recovered charge			-	1	-	nC

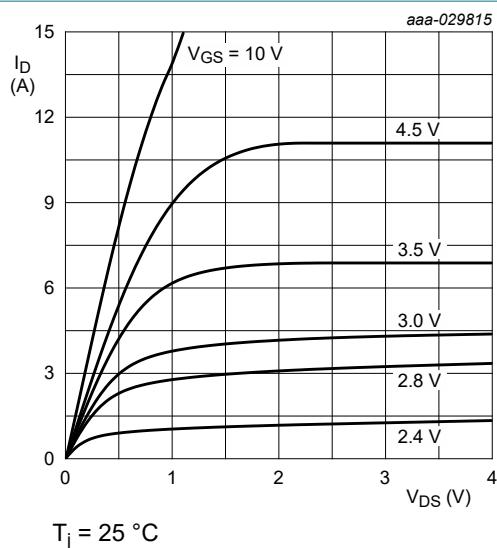


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

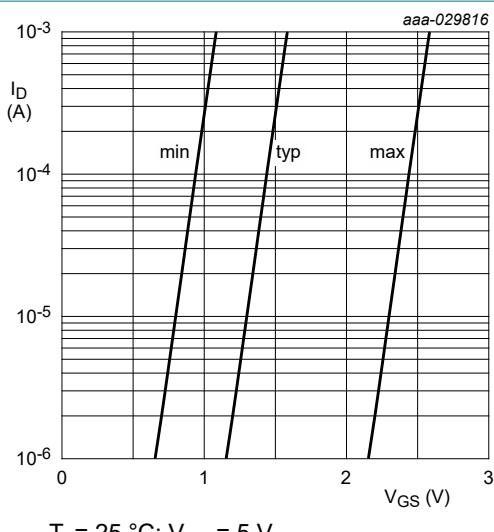


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

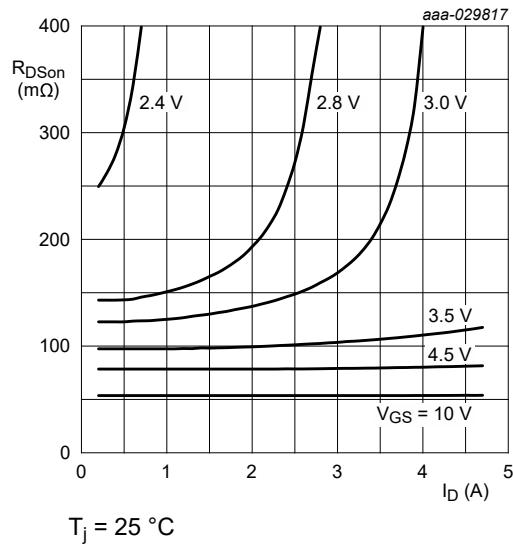


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

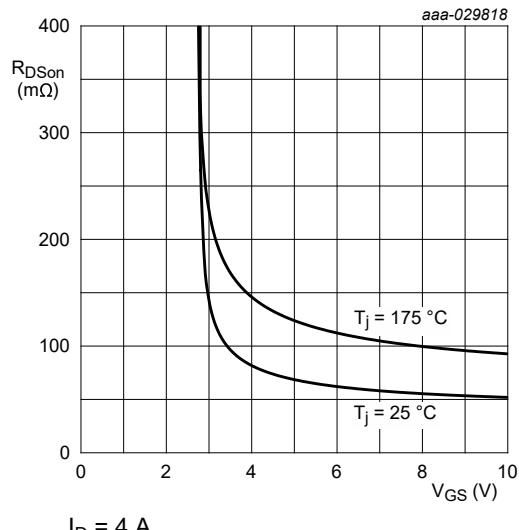
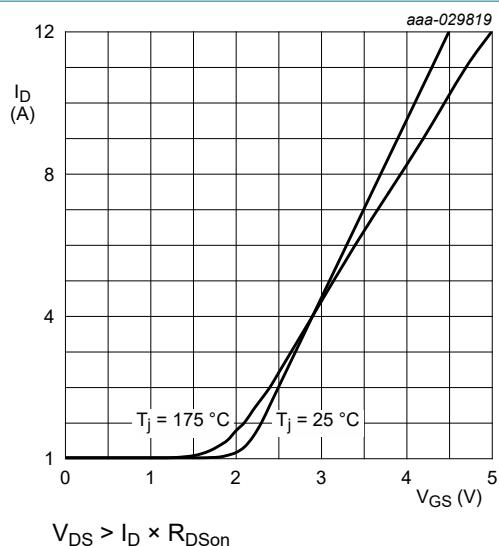
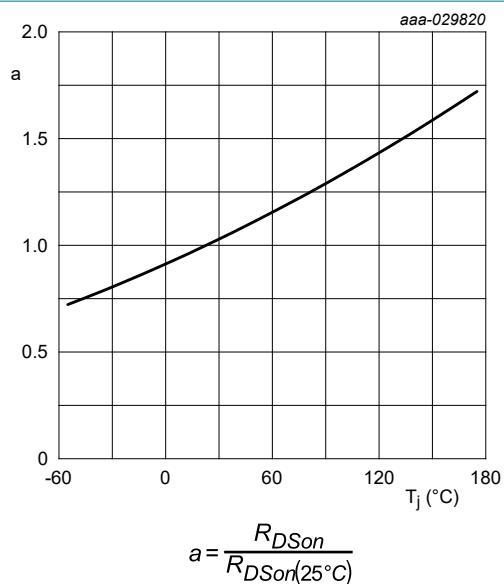


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



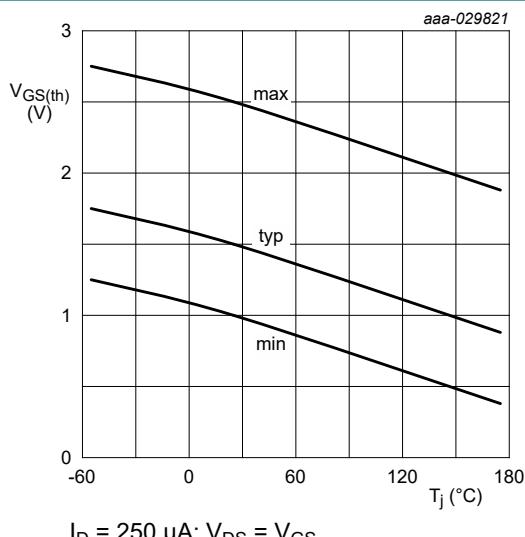
$V_{DS} > I_D \times R_{DSon}$

Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



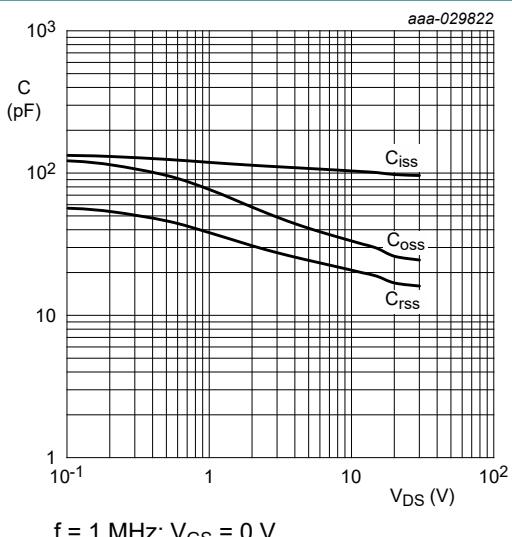
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



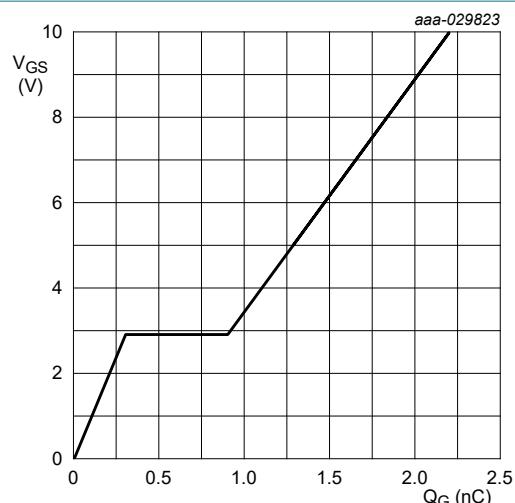
$I_D = 250 \mu\text{A}; V_{DS} = V_{GS}$

Fig. 12. Gate-source threshold voltage as a function of junction temperature



$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 3$ A; $V_{DS} = 15$ V; $T_{amb} = 25$ °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

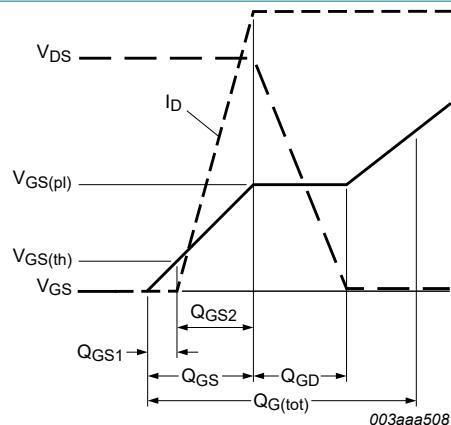
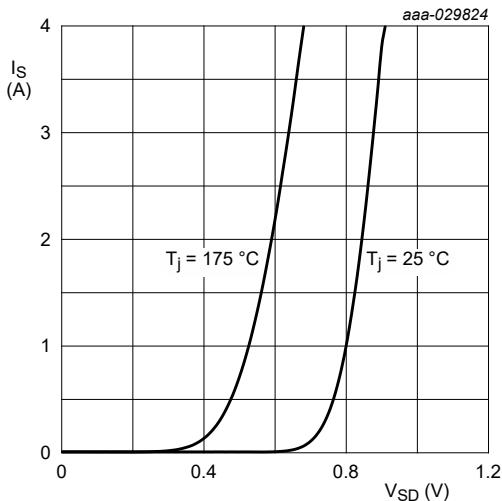


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

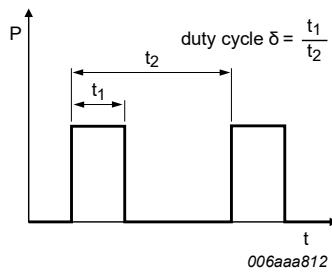
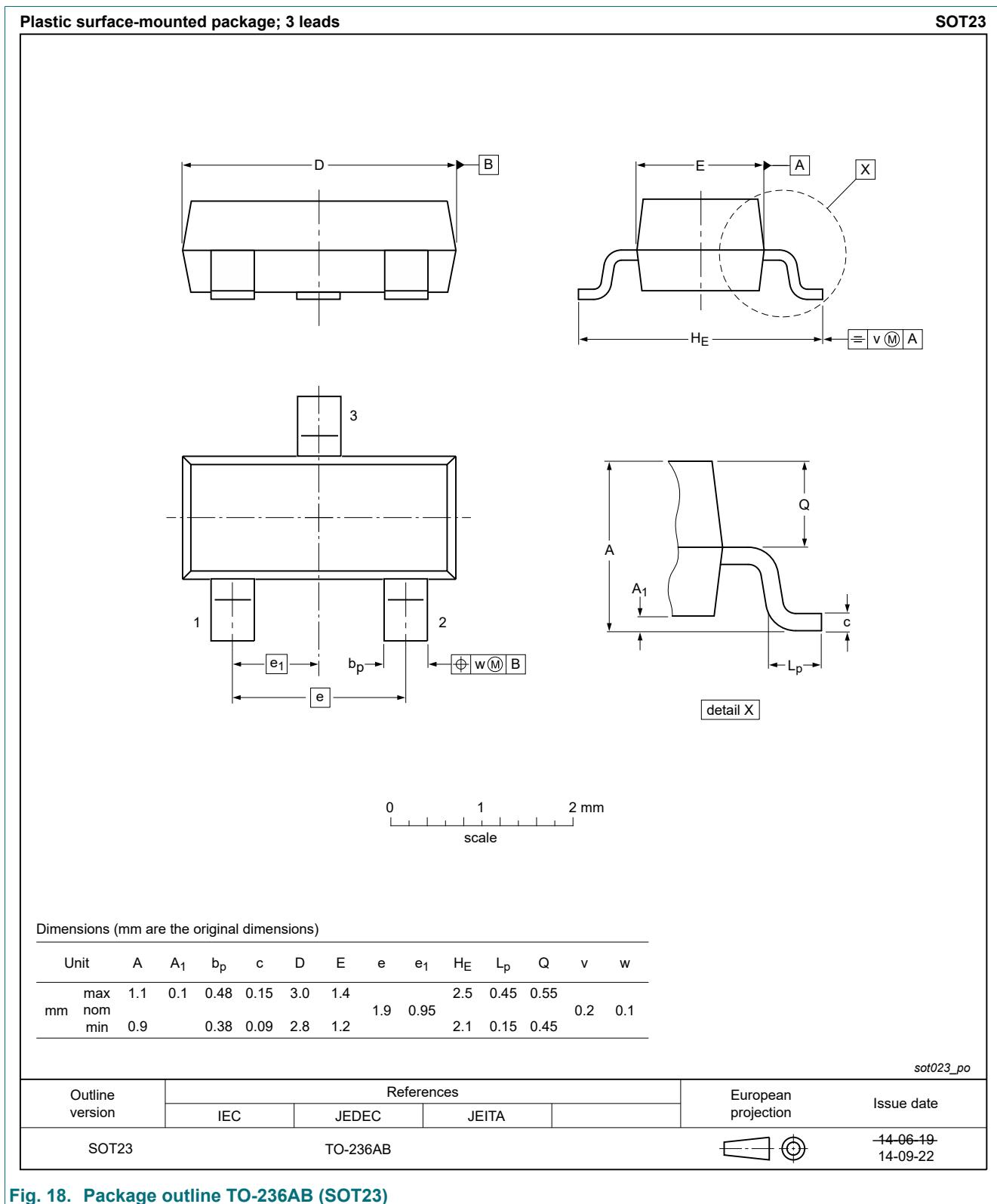


Fig. 17. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering

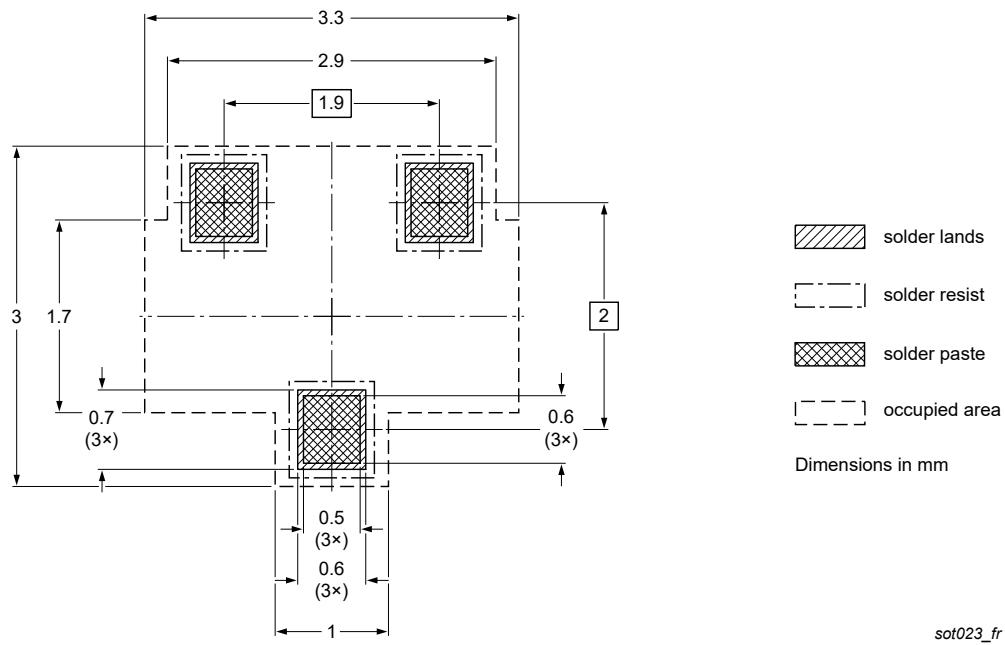


Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)

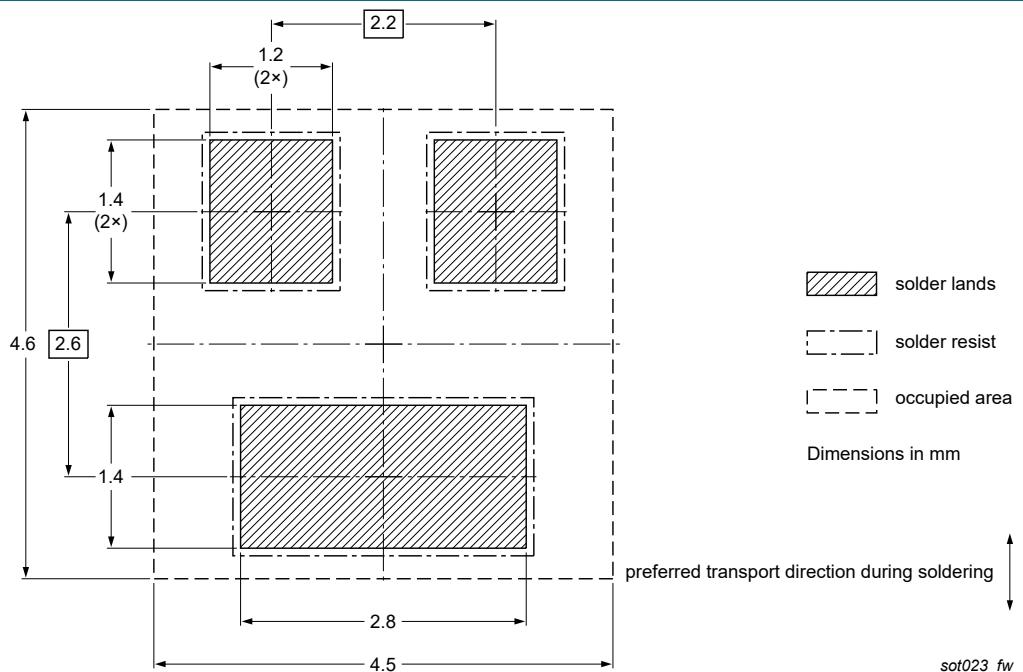


Fig. 20. Wave soldering footprint for TO-236AB (SOT23)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMV52NEA v.1	20190507	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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